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From: Charles A. Brill
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Mezennner

Art Unit: 2873

Serial No.: 10/749,277

Examiner: Dinh, Jack

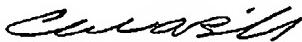
Filed: 31 December 2003

Docket No. TI-33824

For: VIA ADHESION IN MULTILAYER MEMS STRUCTURE

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office on the date shown below:


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NAME OF INVENTOR(S):	
Mezennner	
TITLE OF INVENTION:	
VIA ADHESION IN MULTILAYER MEMS STRUCTURE	
TI FILE NO.:	DEPOSIT ACCT. NO.:
TI-33824	20-0668
FAXED: 12/02/2005	
DUE:	
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RECEIPT DATE & SERIAL NO.:	
Application No.: 10/749,277	
Filing Date: 31 December 2003	

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Texas Instruments Incorporated
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Mezennier

Art Unit: 2873

Serial No.: 10/749,277

Examiner: Dinh, Jack

Filed: 31 December 2003

Docket No. TI-33824

For: VIA ADHESION IN MULTILAYER MEMS STRUCTURE

COMMUNICATION

2 December 2005

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MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8 (a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, Virginia, 22313-1450, or facsimile transmitted to the U.S. Patent and Trademark Office, on the date shown below.

2 Dec. 2005

Charles A. Brill

Date

Dear Sir:

In a telephone call on 1 December 2005, Ms. Amanda Ford informed the applicant that the U.S.P.T.O. does not have a complete copy of the amendment in response to the Examiner's Action facsimile transmitted to the U.S.P.T.O. on 11 November 2005. Ms. Ford stated the request for an extension of time was received, and requested the applicant resubmit the entire amendment. Accordingly, it is believed no petition or fee is required.

From the applicant's fax confirmation and the two auto-replies received by the applicant, it appears that the transmission was received by the U.S.P.T.O. as two separate transmissions—one of which was not identifiable and was therefore unable to be matched to the proper file.

Copies of the original coversheet, original amendment, facsimile confirmation, and two auto-replies accompany this communication.

Respectfully submitted,

Charles A. Brill
 Reg. No. 37,786

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P.03/16

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Mezennier

Art Unit: 2873

Serial No.: 10/749,277

Examiner: Dinh, Jack

Filed: 31 December 2003

Docket No. TI-33824

For: VIA ADHESION IN MULTILAYER MEMS STRUCTURE

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NAME OF INVENTOR(S):	
Mezennier	
TITLE OF INVENTION:	
VIA ADHESION IN MULTILAYER MEMS STRUCTURE	
FILE NO.:	DEPOSIT ACCT. NO.:
TI-33824	20-0668
FAXED: 11/11/2005	
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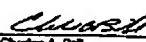
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<p>To: Technology Center 2800 Facsimile Number: 571-273-8300 Total Pages Sent 13</p> <p>From: Charles A. Brill 571-273-8300</p> <p>Texas Instruments Incorporated Facsimile: 972-917-4418 Phone: 972-917-4379</p> <p>IN THE UNITED STATES PATENT AND TRADEMARK OFFICE</p> <p>Applicant: Mezennier Art Unit: 2873 Serial No.: 10/749,277 Examiner: Dinh, Jack Filed: 31 December 2003 Docket No. TI-33824</p> <p>For: VIA ADHESION IN MULTILAYER MEMS STRUCTURE</p> <p>CERTIFICATION OF FACSIMILE TRANSMISSION I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office on the date shown below:  Charles A. Brill November 11, 2005 Date</p> <p>FACSIMILE COVER SHEET</p> <table border="1"><tr><td><input checked="" type="checkbox"/> FACSIMILE COVER SHEET</td><td><input type="checkbox"/> AMENDMENT (11 Pages)</td></tr><tr><td><input type="checkbox"/> NEW APPLICATION</td><td><input type="checkbox"/> EOT (1 Page)</td></tr><tr><td><input type="checkbox"/> DECLARATION (1 Page)</td><td><input type="checkbox"/> NOTICE OF APPEAL</td></tr><tr><td><input type="checkbox"/> ASSIGNMENT (1 Page)</td><td><input type="checkbox"/> APPEAL BRIEF (3 Pages)</td></tr><tr><td><input type="checkbox"/> POWER OF ATTORNEY</td><td><input type="checkbox"/> RPLY BRIEF (3 Pages)</td></tr><tr><td><input type="checkbox"/> INFORMATION SHEET</td><td><input type="checkbox"/> PETITION</td></tr><tr><td><input type="checkbox"/> CONTINUATION APPN (0 Pages)</td><td><input type="checkbox"/> ISSUE FEE (0 Pages)</td></tr><tr><td><input type="checkbox"/> DIVISIONAL APPN</td><td></td></tr><tr><td colspan="2">NAME OF INVENTOR</td></tr><tr><td colspan="2">Mezennier</td></tr><tr><td colspan="2">TITLE OF INVENTION</td></tr><tr><td colspan="2">VIA ADHESION IN MULTILAYER MEMS STRUCTURE</td></tr><tr><td>FILE NO.</td><td>DEPOSIT ACCT #:</td></tr><tr><td>TI-33824</td><td>2D-0608</td></tr><tr><td>FILED: 11/11/2005</td><td></td></tr><tr><td>DUE: 9/12/2006</td><td></td></tr><tr><td>ATTY/SECT: CABA</td><td></td></tr></table> <p>This facsimile is intended only for the use of the addressee named and contains legally privileged and/or confidential information. If you are not the intended recipient of this facsimile, you are hereby notified that any dissemination, distribution, copying or use of this facsimile is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by facsimile. Any inadvertent disclosure should be returned to the sender by mail at the address indicated on this cover sheet.</p> <p>Texas Instruments Incorporated PO Box 650474, MS 2200 Dallas, TX 75265</p>			<input checked="" type="checkbox"/> FACSIMILE COVER SHEET	<input type="checkbox"/> AMENDMENT (11 Pages)	<input type="checkbox"/> NEW APPLICATION	<input type="checkbox"/> EOT (1 Page)	<input type="checkbox"/> DECLARATION (1 Page)	<input type="checkbox"/> NOTICE OF APPEAL	<input type="checkbox"/> ASSIGNMENT (1 Page)	<input type="checkbox"/> APPEAL BRIEF (3 Pages)	<input type="checkbox"/> POWER OF ATTORNEY	<input type="checkbox"/> RPLY BRIEF (3 Pages)	<input type="checkbox"/> INFORMATION SHEET	<input type="checkbox"/> PETITION	<input type="checkbox"/> CONTINUATION APPN (0 Pages)	<input type="checkbox"/> ISSUE FEE (0 Pages)	<input type="checkbox"/> DIVISIONAL APPN		NAME OF INVENTOR		Mezennier		TITLE OF INVENTION		VIA ADHESION IN MULTILAYER MEMS STRUCTURE		FILE NO.	DEPOSIT ACCT #:	TI-33824	2D-0608	FILED: 11/11/2005		DUE: 9/12/2006		ATTY/SECT: CABA	
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NOV-11-2005 19:05	TI DLP(tm) BUS SVCS	214 567 7859	P.05/13
<p>AMENDMENTS TO THE SPECIFICATION:</p> <p>Please replace the paragraph beginning on line 20 of page 7 with the following rewritten paragraph:</p> <p>The DMD mirrors 14a typically range from 10 um to 16 um square and made of aluminum for maximum reflectivity. They are arrayed on 11 um to 17 um centers to form a dense matrix of pixels. The hinge layer 13 under the mirrors 14a permits a close spacing of the mirrors 14a, and because of the underlying placement of the hinges, an array of pixel elements 10 is referred to as a "hidden hinge" type DMD architecture.</p> <p>Please replace the paragraph beginning on line 5 of page 9 with the following rewritten paragraph:</p> <p>A spacer layer 21, identified as S1, is then deposited over the M3 layer 12 [[+4]]. Spacer layer 21 may be formed from hardened photoresist. Later in the packaging flow, this spacer layer 21 is plasma-etched to form an air gap. A number of vias are then formed in spacer layer 21, formed by conventional pattern and etching techniques.</p> <p>Please replace the paragraph beginning on line 16 of page 9 with the following rewritten paragraph:</p> <p>FIGURES 4 - 6 illustrate fabrication of hinge layer 13. As explained below, hinge layer 13 contains both hinge 13a, spring tips 13b, and spring tip beams 13c (shown in Figures 1 and 7) from which the spring tips extend.</p> <p>Please replace the paragraph beginning on line 26 of page 9 with the following rewritten paragraph:</p> <p>FIGURE 5 illustrates a portion of the partially fabricated DMD having a via 31, similar to vias 32 [[+6]] and 33 of Figure 3, and the result of a patterned etch process. The etch leaves an oxide coating within the via(s) 31,32,or 33. The oxide at the bottom of the via covers the thin metal at the bottom of each via, thereby providing strengthening. A develop step is then performed, or other cleaning to remove residue and prevent surface contamination. As an</p>			

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